



Product Change Notification / BLAS-27GJUK085

Date:

11-Jul-2024

Product Category:

32-Bit Microcontrollers

PCN Type:

Manufacturing Change

Notification Subject:

CCB 7046 Initial Notice: Qualification of ATP7 as an additional assembly site for selected ATSAM4S16C, ATSAM4S2C, ATSAM4S4C, ATSAM4S8C, ATSAM4SA16C, ATSAM4SD16C and ATSAM4SD32C device families available in 100L TFBGA (9x9x1.2mm) package.

Affected CPNs:

[BLAS-27GJUK085_Affected_CPN_07112024.pdf](#)
[BLAS-27GJUK085_Affected_CPN_07112024.csv](#)

Notification Text:

PCN Status:Initial Notification

PCN Type:Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Qualification of ATP7 as an additional assembly site for selected ATSAM4S16C, ATSAM4S2C, ATSAM4S4C, ATSAM4S8C, ATSAM4SA16C, ATSAM4SD16C and ATSAM4SD32C device families available in 100L TFBGA (9x9x1.2mm) package.

Pre and Post Change Summary:

	Pre Change	Post Change	
Assembly Site	ATX Semiconductor (Shanghai) Co. Ltd (ASSH)	ATX Semiconductor (Shanghai) Co. Ltd (ASSH)	Amkor Technology Philippines (P3/P4), INC. (ATP7)
Substrate Core Material	CCL-HL832NX	CCL-HL832NX	HL832NXA
Substrate Core Thickness	100±30 UM	100±30 UM	100 UM
Substrate SM Material	AUS308	AUS308	AUS308
Substrate SM Thickness	30+/-15 UM	30+/-15 UM	30+/-10 UM
Wire Material	CuPd	CuPd	CuPdAu
Die Attach Material	2100AS	2100AS	2300
Molding Compound Material	KE-G1250LKDS	KE-G1250LKDS	G770FE
Solder Ball Material	SAC105	SAC105	SAC105

Impacts to Data Sheet:None

Change Impact:None

Reason for Change: To improve on-time delivery performance by qualifying ATP7 as an additional assembly site.

Change Implementation Status: In Progress

Estimated Qualification Completion Date: November 2024

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

Date								
Qual Report Availability								X
Final PCN Issue Date								X

Method to Identify Change:Traceability code

Qualification Plan:Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History:July 08, 2024: Issued initial notification.

July 11, 2024: Re-issued initial notification. Corrected PCN number.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

[PCN_BLAS-27GJUK085 Qual Plan.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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